IPC ASSOCIATION ELECTRONIC	Material Compo © Copyright 2005. If SINDUSTRIES® international and Pan	C, Bannockb	urn, Illinois. A	ll rights reserved untions.	nder both	This docume level parts, the	ent is a declara he declaration	ntion of the	ne substances asses all lowe	within the	e manufactur terials for w	rer listed it thich the m	em. Note: anufactur	: if the item is an as rer has engineering	sembly with low responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					ials and Mf	als and Mfg Information			
Supplie	r Information														
Company	name*	Company uni	Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-04-17			
Contact N	lame		Title - Contact]	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing Si		iring Site	Weight*		UOM	Unit Type		
		AP1302C A0-DR			MP Co-Processor		2024-04-17		1	MY5		6	8.1	mg	Each
I anufa	cturing Proccess Informat	ion													
	Terminal Plating / Grid Array Material T		Ferminal Base Alloy J-STD-		-STD-020 MSL	Rating	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperatu	ıre Nun	nber of Reflow Cyc	eles	
	SnAgCu		CU Alloy 4		ļ		260 C		30 seco		secono	is 3			
omments	3														
or more	information regarding material	composition j	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.02	mg	Supplier	Silicon (Si)	7440-21-3		7.9903	mg
			Supplier	Polyimide	Proprietary Data		0.0297	mg
Die Attach	0.8	mg	Supplier	Epoxy resins	129915-35-1		0.06	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.436	mg
			Supplier	Acrylic resins	Proprietary Data		0.084	mg
			Supplier	Polyimide	Proprietary Data		0.22	mg
Mold Compound-Black	33.8	mg		Phenolic Resin	proprietary data		1.521	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		2.028	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1014	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.014	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.6542	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.4814	mg
Solder Ball	12.56	mg	Supplier	Silver (Ag)	7440-22-4		0.3768	mg
			Supplier	Tin (Sn)	7440-31-5		12.1204	mg
			Supplier	Copper (Cu)	7440-50-8		0.0628	mg
Substrate and Solder Mask	12.31	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		2.6085	mg
			В	Nickel (Ni)	7440-02-0		0.2339	mg
			Supplier	Gold (Au)	7440-57-5		0.0308	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		1.7505	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		1.6101	mg
			Supplier	Copper (Cu)	7440-50-8		6.0762	mg
Wire Bond - Au	0.61	mg	Supplier	Gold (Au)	7440-57-5		0.61	mg